B-2382 V3.2C Specification Drawing

B-2382 V3.2C PC BOARD SPECIFICATIONS

1. Board Layers: 8
2. Layer Stack Order:
   - Layer 1: Top component layer (signal_1)
   - Layer 2: Power plane (Vcc, AVCC)
   - Layer 3: Inner signal layer (signal_3)
   - Layer 4: Power plane (AGND)
   - Layer 5: Power plane (GROUND)
   - Layer 6: Inner signal layer (signal_4)
   - Layer 7: Power plane (VEE, VCC2)
   - Layer 8: Bottom component layer (signal_2)
3. Apply silkscreen on both sides:
   - Film 9: Top component side silkscreen
   - Film 10: Bottom component side silkscreen
4. Apply solder mask over bare copper on both sides:
   - Film 11: Top component side solder mask
   - Film 12: Bottom component side solder mask
5. Material: FR4
6. Board thickness: 0.062'' +/- 0.010
7. Board outline is metric
8. All layers are equal thickness
9. Copper thickness 1oz before plating
10. All dimensions are in inches unless otherwise noted

BOARD'S DRILL SCHEDULE (unit: inch)

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<th>DRILL SIZE</th>
<th>COUNT</th>
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Note: Rev. v3.2c interchanges label for layer 4 and layer 5 in item 2 (layer stack order) above.